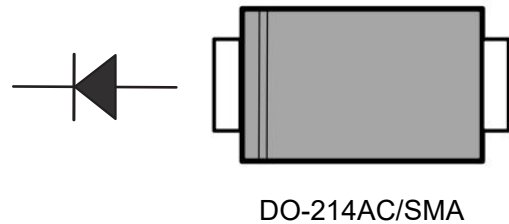


Surface Mount Superfast Recovery Rectifiers

Parameter	Value	Unit
V_{RRM}	50~600	V
$I_{F(AV)}$	2.0	A
T_{RR}	35	ns



DO-214AC/SMA

Features

- For surface mounted applications
- Low profile package
- Glass Passivated Chip Junction
- Easy to pick and place
- Super fast reverse recovery time

Applications

- For use in high-frequency rectification and free-wheeling applications in switching-mode converters and inverters for consumer electronics, computer systems, and telecommunications.

Absolute Maximum Ratings and Characteristics (at $T_J = 25^\circ\text{C}$ unless otherwise specified)

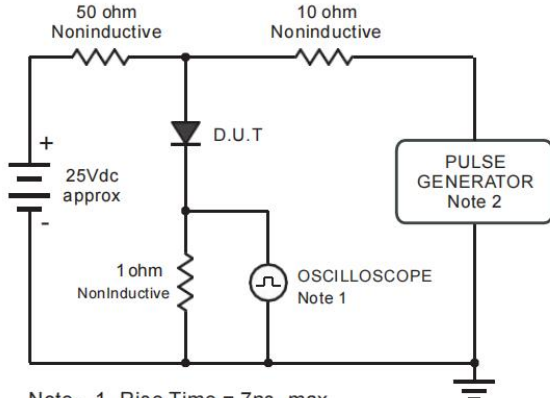
Parameter	Symbol	ES2A	ES2B	ES2C	ES2D	ES2E	ES2G	ES2J	Units	
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	50	100	150	200	300	400	600	V	
Maximum RMS voltage	V_{RMS}	35	70	105	140	210	280	420	V	
Maximum DC Blocking Voltage	V_{DC}	50	100	150	200	300	400	600	V	
Maximum Average Forward Rectified Current	$I_{F(AV)}$	2.0							A	
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load(JEDEC Method)	I_{FSM}	50							A	
Maximum Forward Voltage at 2A	V_F	1				1.25		1.70	V	
Maximum DC Reverse Current at Rated DC Blocking Voltage	I_R					5		100		μA
Typical Junction Capacitance at $V_R=4\text{V}$, $f=1\text{MHz}$	C_j	15							pF	
Maximum Reverse Recovery Time (1)	t_{rr}	35							ns	
Typical Thermal Resistance (2)	$R_{\theta JA}$	75							$^\circ\text{C}/\text{W}$	
Operating and Storage Temperature Range	T_J, T_{stg}	-55 ~ +150							$^\circ\text{C}$	

Notes:

- (1) Measured with $I_F = 0.5\text{A}$, $I_R = 1\text{A}$, $I_{rr} = 0.25\text{A}$.
 (2) P.C.B. mounted with 2.0" X 2.0" (5 X 5cm) copper pad areas.

Typical characteristics

Fig.1 Reverse Recovery Time Characteristic And Test Circuit Diagram



Note: 1. Rise Time = 7ns, max.
Input Impedance = 1megohm, 22pF.
2. Rises Time = 10ns, max. Source Impedance = 50 ohms.

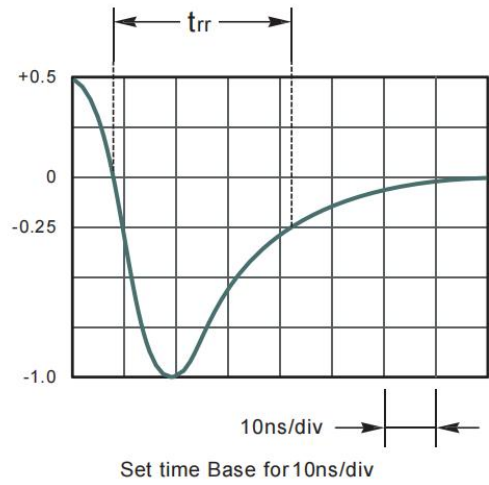


Fig.2 Maximum Average Forward Current Rating

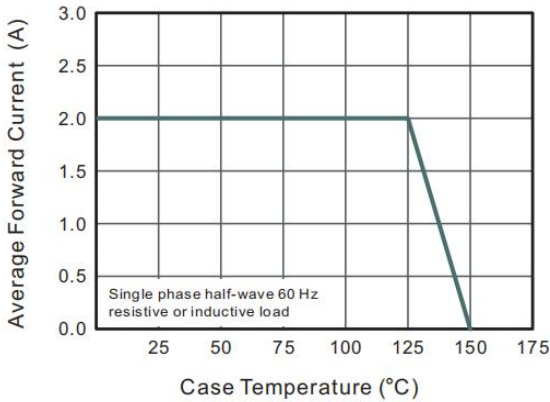


Fig.3 Typical Reverse Characteristics

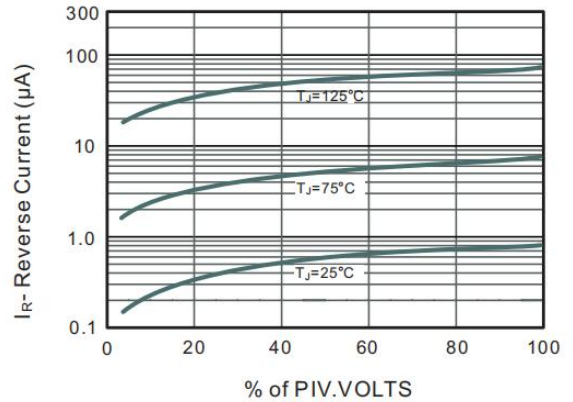


Fig.4 Typical Forward Characteristics

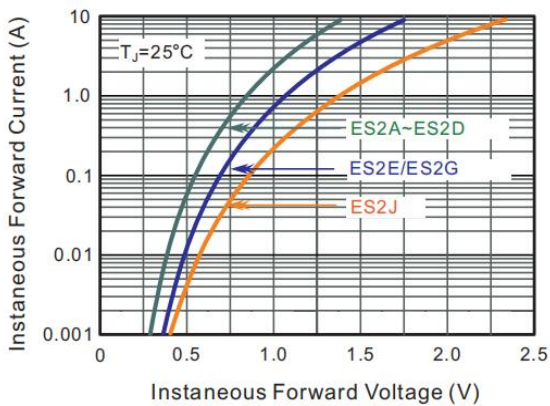


Fig.5 Typical Junction Capacitance

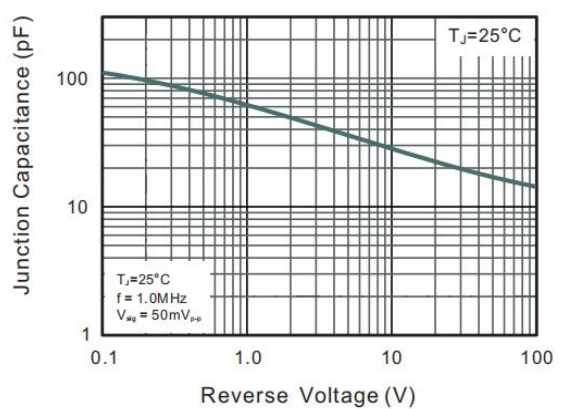
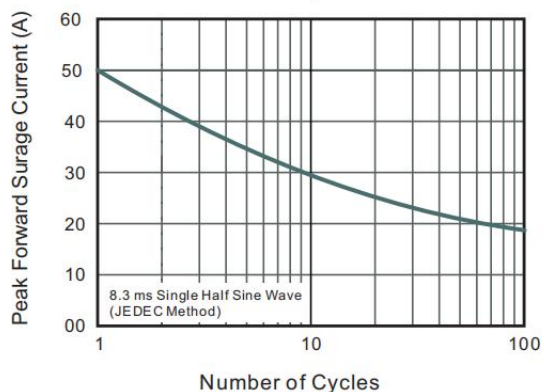


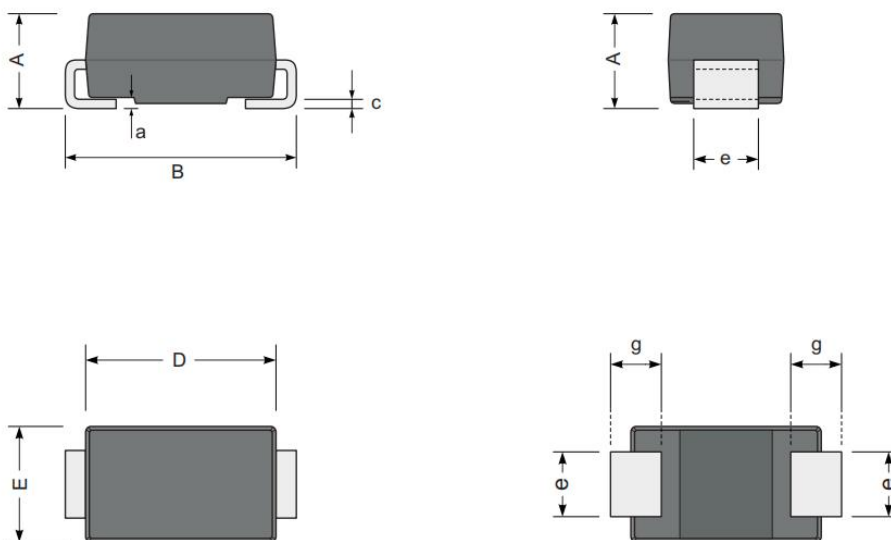
Fig.6 Maximum Non-Repetitive Peak Forward Surge Current



Package outlines

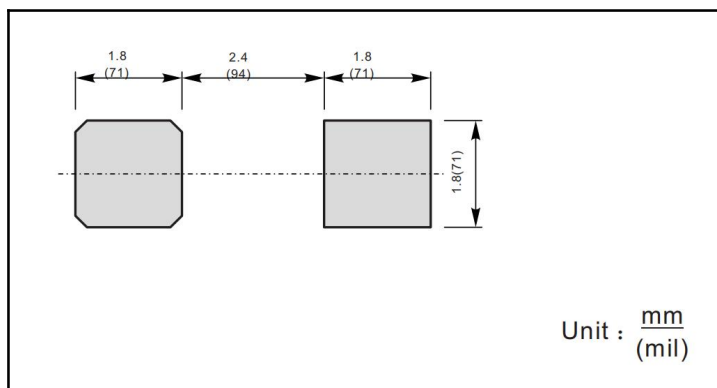
Plastic surface mounted package; 2 leads

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UNIT		A	D	E	B	c	e	g	a
mm	max	2.2	4.5	2.8	5.3	0.31	1.6	1.5	0.3
	min	1.9	4.0	2.4	4.8	0.15	1.3	0.9	
mil	max	87	181	110	209	12	63	59	12
	min	75	157	94	189	6	51	35	

The recommended mounting pad size



Marking

Type number	Marking code
ES2A	ES2A
ES2B	ES2B
ES2C	ES2C
ES2D	ES2D
ES2E	ES2E
ES2G	ES2G
ES2J	ES2J

*Important Usage Information and Disclaimer

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